

SPECIFICATION

COMMERCIALLY AVAILABLE

CERAMIC MONOBLOCK
PART NUMBER: CFM-06500026
RoHS

03/24/2021 – Updated dimensions

ISSUED / REVISION	ENGINEER APPROVED	DOCUMENT CHECKED	DRAFTSMAN	DOCUMENT CHECKED
7/9/08 **				
1/11/12 DS	10/08/2013 TFG		10/08/2013 GL	
03/24/2021 ^{ASM}	03/24/2021 ^{TG}			

FILTRONETICS Inc

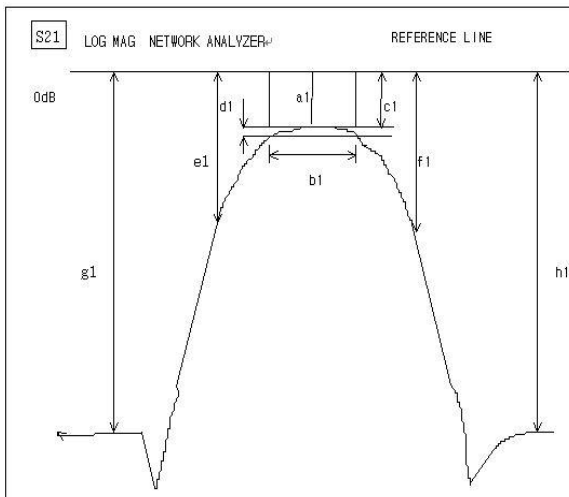
1. PART NUMBER

PART NO	CFM-06500026
PACKAGING	TAPE AND REEL

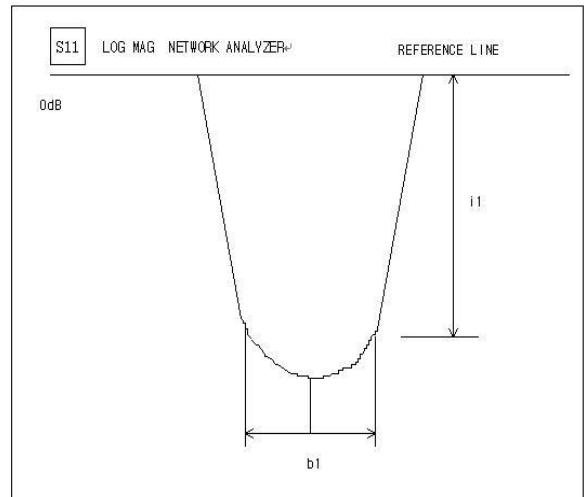
2. SPECIFICATIONS:

NO	Parameter	Ref.	Typ.	Spec.
1	Center Frequency (Fo)	a1	650 MHz	
2	Pass Bandwidth (BW)	b1	649 ~ 651 MHz	
3	Insertion Loss in BW	c1	5.8 dB	6.3 dB Max.
4	3 dB Bandwidth	b1		8 MHz Max.
5	Ripple in BW	d1	0.3 dB	0.8 dB Max.
6	Return Loss in BW	i1	17 dB	15 dB Min.
7	Attenuation	At 639 MHz	e1	50 dB
		At 661 MHz	f1	50 dB
8	Input Power		3 W Max.	
9	Operating Temperature		-40 to +85°C	
10	Impedance		50 ohm	

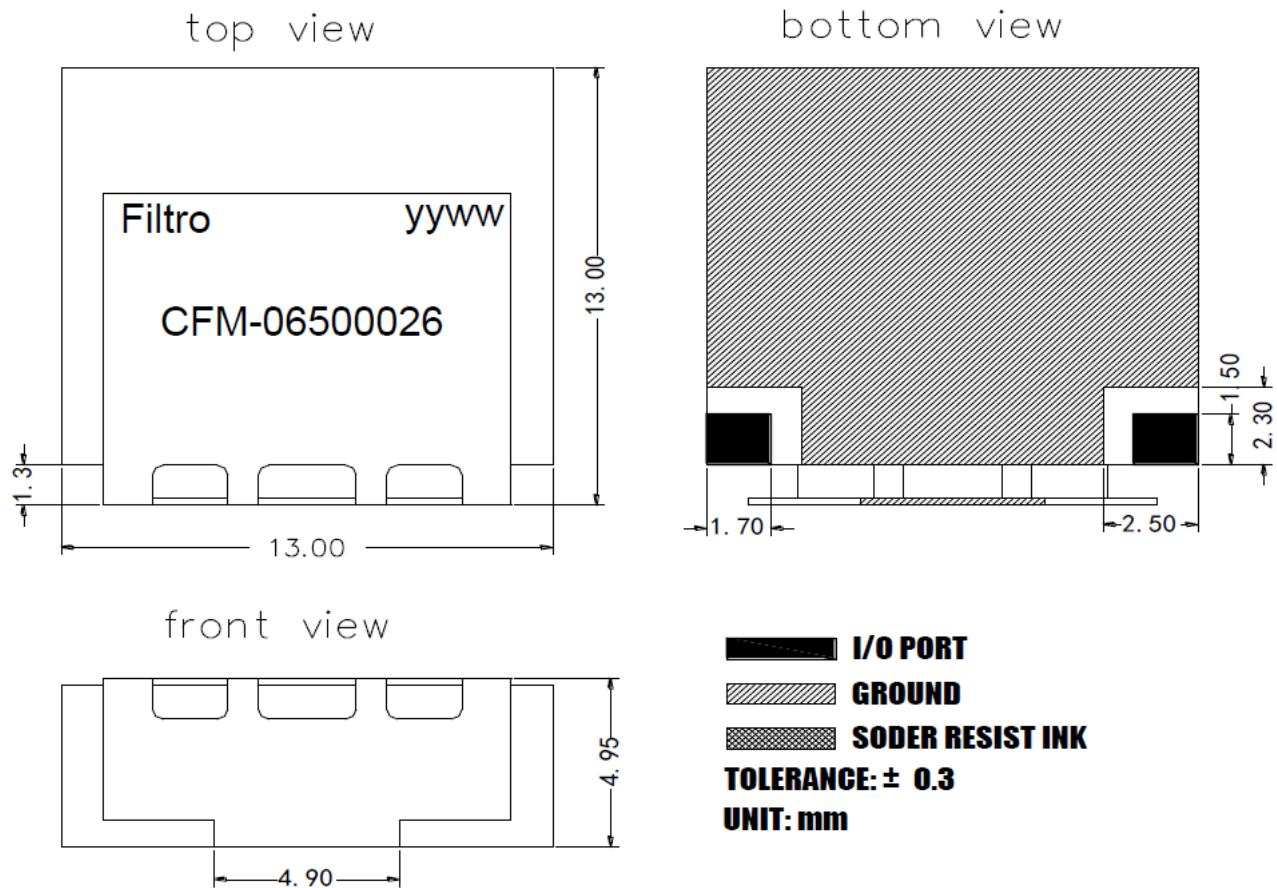
S21 LOG MAG NETWORK ANALYZER



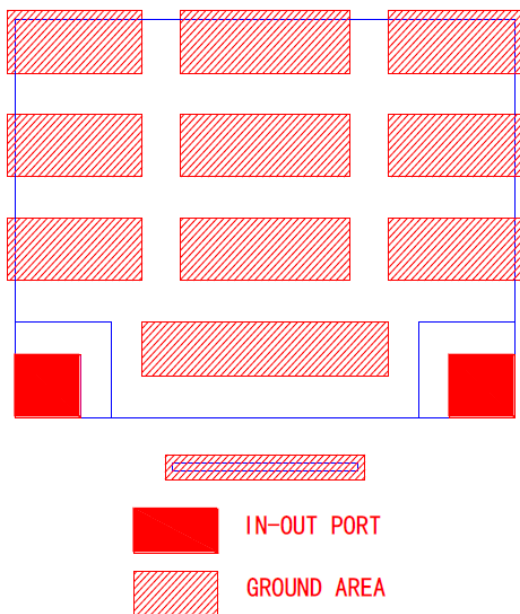
S11 LOG MAG NETWORK ANALYZER



3. DIMENSIONS:

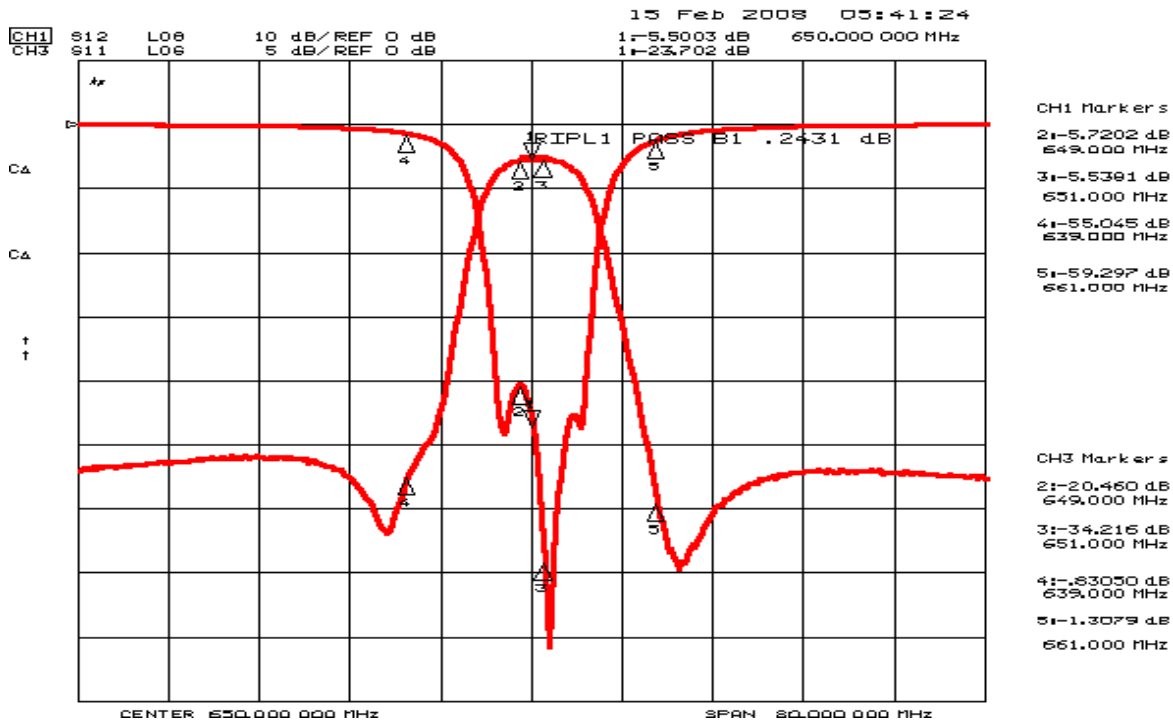


Recommended solder land pattern

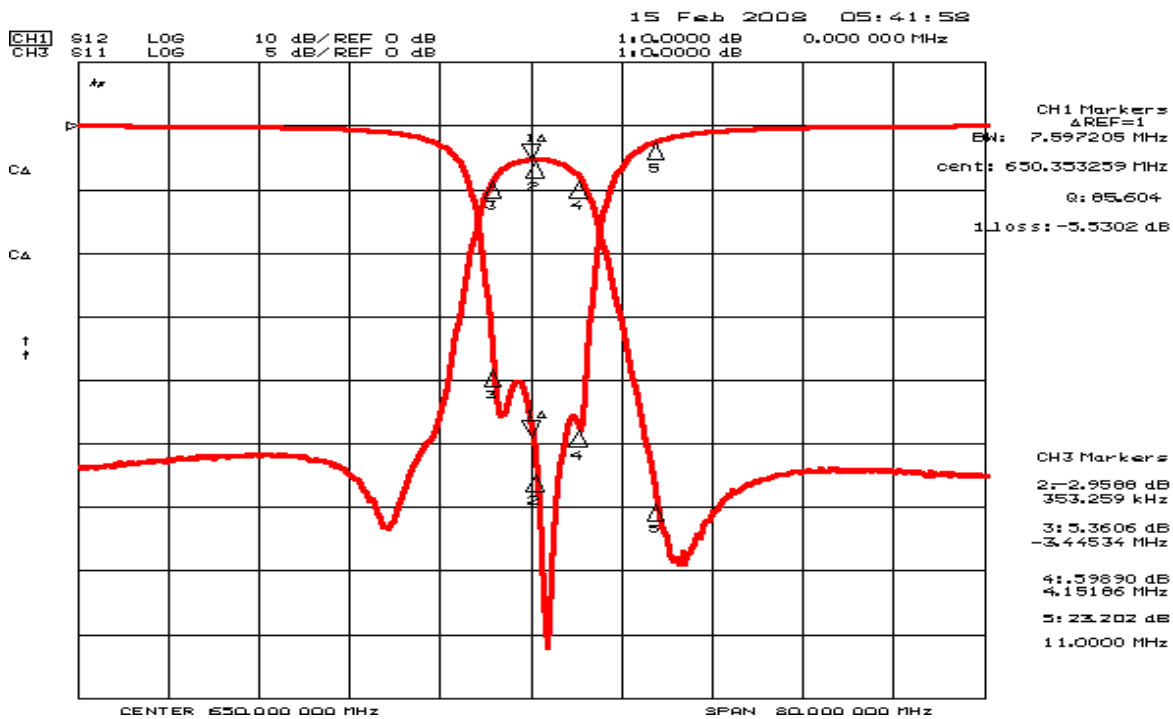


4. GRAPHS

S21 & S11 (INSERTION LOSS, RIPPLE, RETURN LOSS, ATTENUATION AT 639, 661 MHz)



S21 & S11 (3 dB BANDWIDTH)



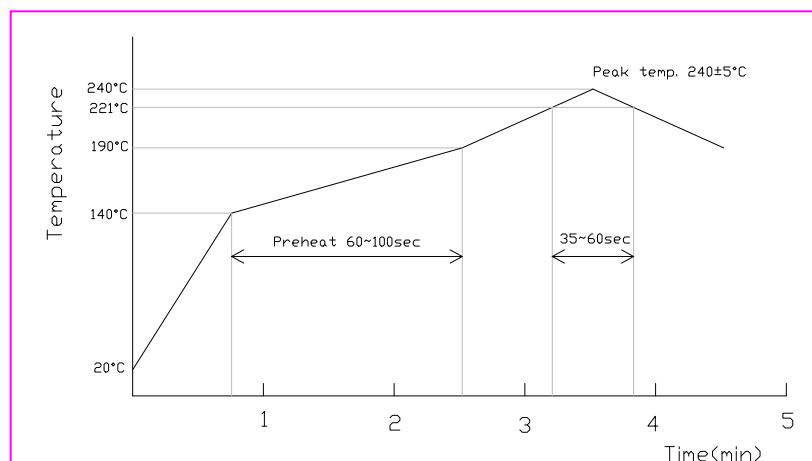
5. DEFINITIONS

TERMS	DESCRIPTION	SPECIFICATION
Center Frequency	The midpoint of through band pass filter pass band, normally expressed as the arithmetic mean of the -3db point. Also called f_0 .	3. SPECIFICATION
Pass Band Width	The width of the pass band of a filter referenced to the minimum insertion loss point in the pass band. The pass band of a filter is stated as -1.0dB bandwidth.	
Insertion Loss	The loss of the filter, in db, measured at center frequency relative to a through line (0 dB).	
Attenuation	Reduction of RF power through a filter measured in dB, at desired band and referenced to 0 dB. (Filter to be removed from circuit)	
Pass Band Ripple	Variations in loss in the pass band of the filter, superimposed upon the fundamental shape of the pass band.	
V.S.W.R in Pass Band	The ratio of the maximum value of a standing wave to its minimum value, related to the return loss in pass band.	

6. RELIABILITY TEST AND CONDITIONS

ITEM	TEST CONDITIONS	REQUIREMENTS
Operating Temp. Range		-40 to +85°C
Resistance to solder heat	Preheat temperature : 120 to 150°C Preheat time: 1 to 1.5 min Solder temperature: 260 +/- 10°C Dipping time: 10 +/- 0.5 sec	No damage such as cracks should be caused in chip element.
Solderability	Preheat temperature: 120 to 150°C Preheat time: 1 to 1.5 min Solder temperature: 235 +/- 5°C Dipping time: 5 +/- 1 sec	More than 80% of the terminal electrode shall be covered with new solder
Heat resistance (High-temperature Load)	Temperature: 85 +/- 2°C Applied voltage: Rated voltage Applied current: Rated current Recovery: 1 to 2hrs of recovery under the standard condition after the removal from test chamber.	No mechanical damage. After test, the device shall satisfy the specification in section 3.
Thermal shock (Temperature cycle)	Conditions for 1 cycle Step 1: + 85°C 15 min Step 2 : - 30°C 15 min Number of cycle: 10	No mechanical damage. After test, the device shall satisfy the specification in section 3.
Humidity Resistance	Temperature: 40 +/- 2°C Humidity: 90 to 95% RH Duration: 96 +/- 5 hrs Recovery: 1 to 2hrs of recovery under the standard condition after the removal from test chamber.	No mechanical damage. After test, the device shall satisfy the specification in section 3.
Vibration	Frequency: 10 ~ 50 Hz Amplitude: 1.52 mm (0.060 inches) Direction: X, Y and Z Time: each 30 min for all directions	No mechanical damage. After test, the device shall satisfy the specification in section 3.

7. REFLOW SOLDERING STANDARD CONDITIONS FOR RoHS



- Measuring point of temperature in-out terminals of the device.
- Reflow Soldering
- Both convection and infrared rays
- Hot air
- Hot plates
- Solder Cream: Sn96.5/Ag3.5